# 2SD2133

## Silicon NPN epitaxial planar type

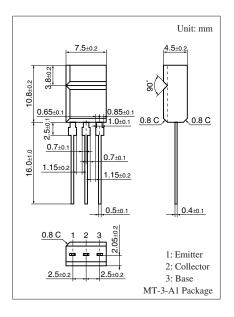
For low-frequency power amplification driver

#### ■ Features

 $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE}(\text{sat})}$ 

### ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_C$	1	A
Peak collector current	$I_{CP}$	1.5	A
Collector power dissipation	P <sub>C</sub>	1.5	W
Junction temperature	$T_{j}$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C



### ■ Electrical Characteristics $T_C = 25$ °C $\pm 3$ °C

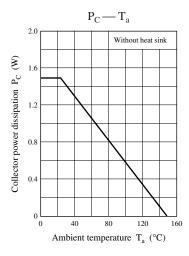
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \ \mu A, I_E = 0$	60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \ \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *1, 2	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}$	85		340	_
	h <sub>FE2</sub> *1	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	50	100		
	h <sub>FE3</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$	35			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.20	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11		pF
(Common base, input open circuited)						

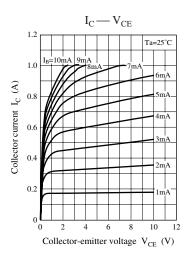
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

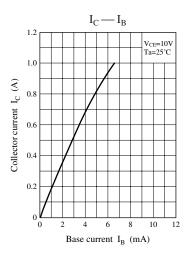
#### \*2: Rank classification

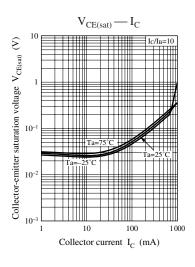
Rank	Q	R	S
$h_{FE1}$	85 to 170	120 to 240	170 to 340

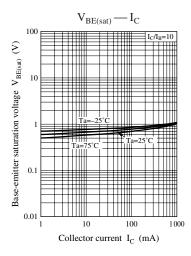
<sup>2. \*1:</sup> Pulse measurement

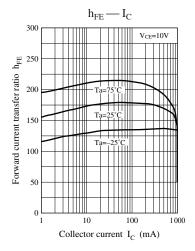


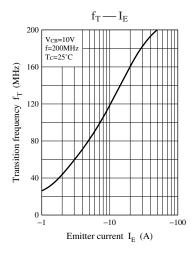


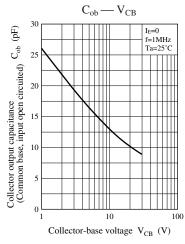


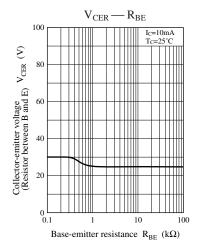


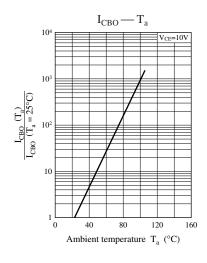


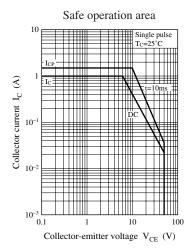


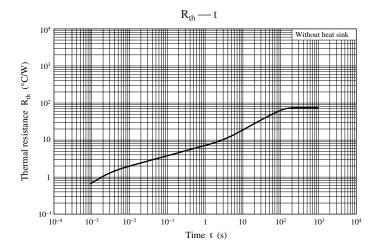












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